HOSTAFORM® S 9243 XAP®2

Impact modified, low emission
POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than the basic type HOSTAFORM® C 9021 Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Preliminary Datasheet

Rheological properties

Melt volume-flow rate	4	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile Modulus	1950	MPa	ISO 527-1/-2
Yield stress, 50mm/min	44	MPa	ISO 527-1/-2
Yield strain, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	40	%	ISO 527-1/-2
Flexural Modulus	1850	MPa	ISO 178
Tensile creep modulus, 1h	1700	MPa	ISO 899-1
Tensile creep modulus, 1000h	950	MPa	ISO 899-1
Charpy impact strength, 23°C	NB	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	200[P]	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	15	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	9	kJ/m^2	ISO 179/1eA

[P]: Partial Break

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	75	°C	ISO 75-1/-2
Vicat softening temperature, 50°C/h, 50N	130	°C	ISO 306
Coeff. of linear therm. expansion, parallel	120	E-6/K	ISO 11359-1/-2

Electrical properties

Relative permittivity, 100Hz	3.8		IEC 62631-2-1
Relative permittivity, 1MHz	3.8		IEC 62631-2-1
Dissipation factor, 100Hz	30	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
Volume resistivity	1E11	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13	Ohm	IEC 62631-3-2
Comparative tracking index	PLC 0	PLC	UL 746A

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Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1	%	Sim. to ISO 62
Density	1330	kg/m³	ISO 1183

Injection

Drying Temperature	100 - 120	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	0.15	%
Screw tangential speed	0.2 - 0.21	m/s
Max. mould temperature	60 - 80	°C
Back pressure	2	MPa
Injection speed	slow-medium	

Characteristics

Additives	Release agent

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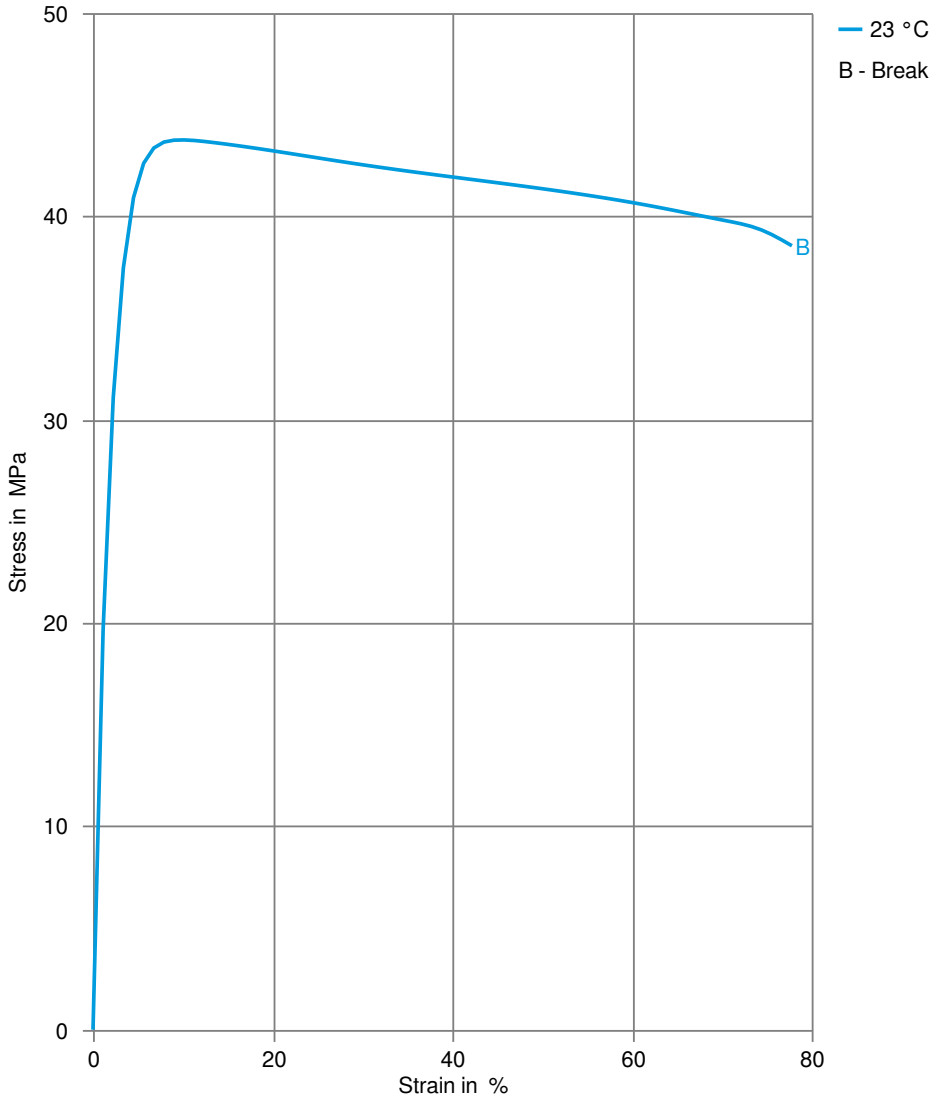
Stress-strain



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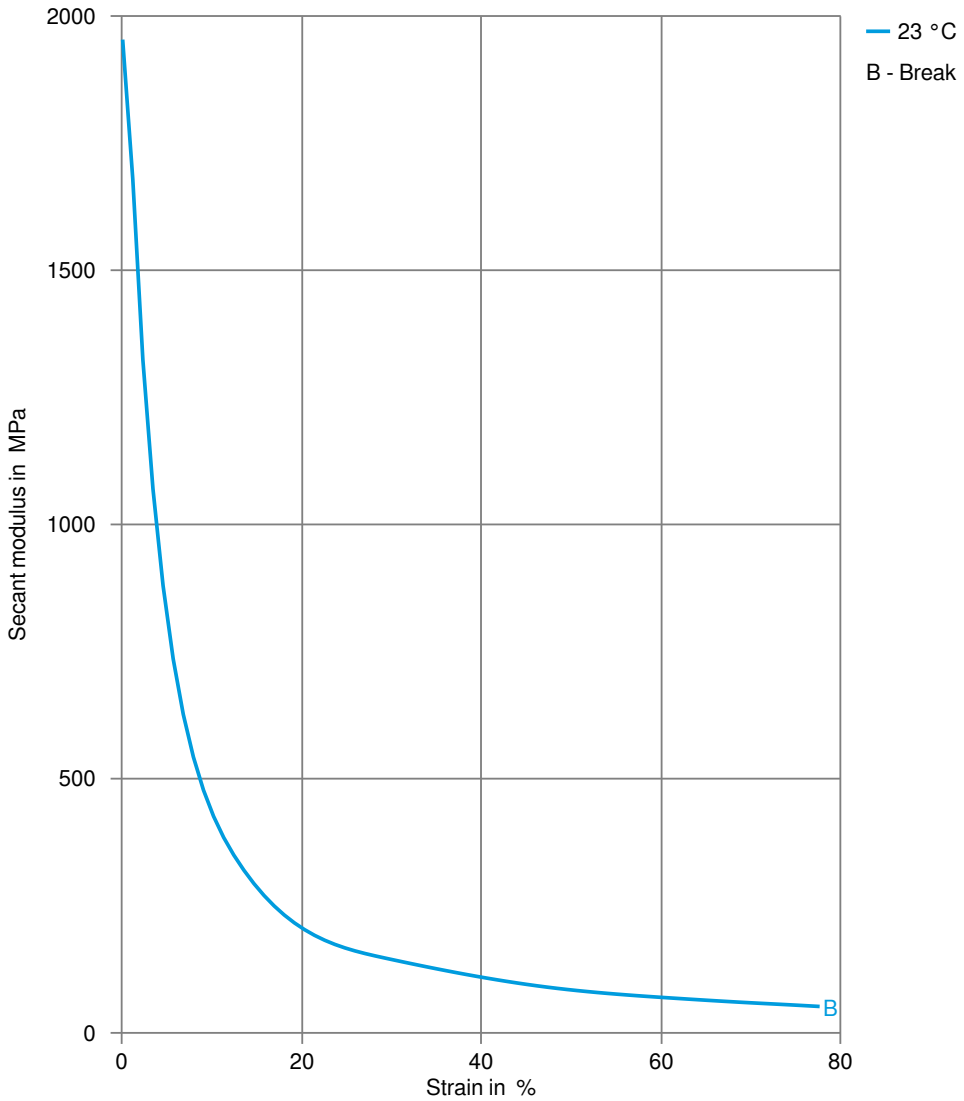
Secant modulus-strain



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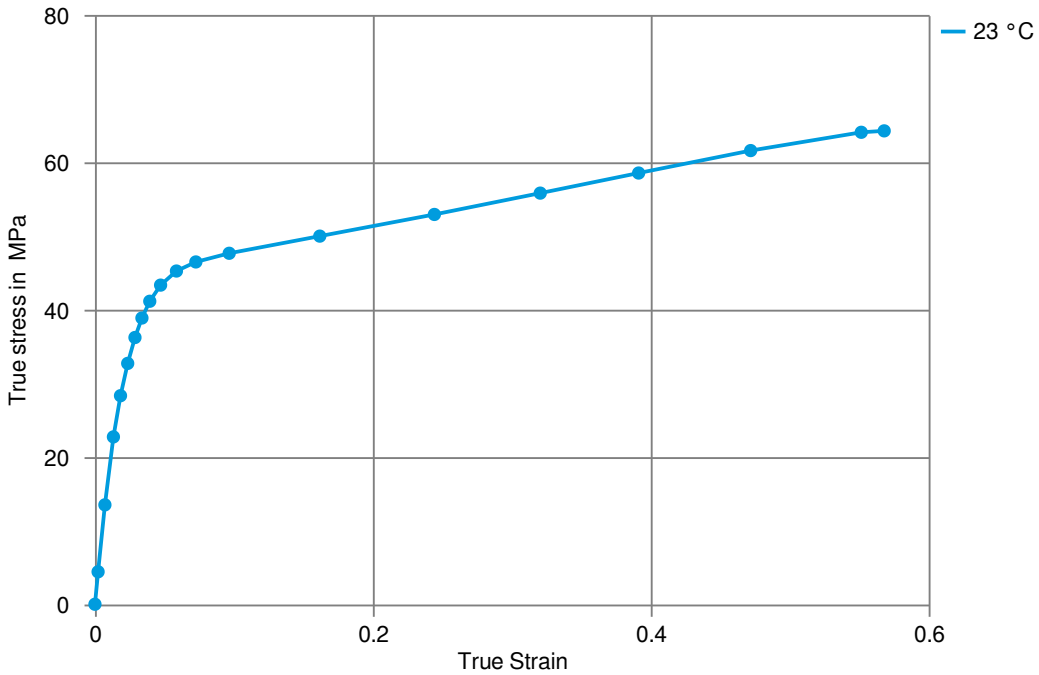
True stress-strain



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Processing Texts

Pre-drying	It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul
Longer pre-drying times/storage	The product can then be stored in standard conditions until processed.

Other Approvals

Other Approvals

OEM	Specification	Additional Information
BJEV	Q-BJEV 01.59	
Mercedes-Benz Group (Daimler)	DBL 5404	Black, BQF
Mercedes-Benz Group (Daimler)	DBL 5410	Black
Renault		No spec listed

Revised: 2023-02-23 Source: Celanese Materials Database